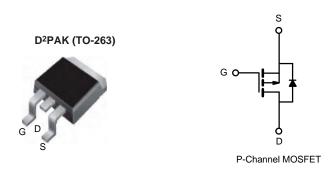


FQB5P10TM-VB Datasheet P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A)	Q _g (Typ.)	
-100	0.22 at V_{GS} = - 10 V	- 12	67	
	0.24 at V _{GS} = - 4.5 V	- 10	07	



FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Power Switch
- Load Switch in High Current Applications
- DC/DC Converters

ABSOLUTE MAXIMUM RATINGS	(T _C = 25 °C, unless oth	nerwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 100	V	
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$)	T _C = 25 °C	1-	- 12		
Continuous Drain Current (1j = 150°C)	T _C = 70 °C	I	- 10	٨	
Pulsed Drain Current (t = 300 µs)		I _{DM}	-40	- A	
Avalanche Current		I _{AS}	- 32		
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	E _{AS} 51		
Maximum Power Dissipation ^a	T _C = 25 °C	D	50.7 ^b	10/	
	T _A = 25 °C ^c	– P _D –	2.1	- W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	°C/W	
Junction-to-Case (Drain)	R _{thJC}	3		

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).

		otherwise noted)				-	
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	T			I			
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_{D} = -250 \mu A$	- 100			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	- 1		- 3.0		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
Zero Gate Voltage Drain Current		$V_{DS} = -100V, V_{GS} = 0V$			- 1		
	I _{DSS}	V_{DS} = - 100 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50	μA	
		V_{DS} = - 80 V, V_{GS} = 0 V, T_{J} = 150 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le$ - 10 V, V_{GS} = - 10 V	- 30			А	
Drain-Source On-State Resistance ^a	P	V _{GS} = - 10 V, I _D = - 14 A		0.22		Ω	
	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 12 A		0.24			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 20 V, I _D = - 14 A		40		S	
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 20 V, f = 1 MHz		2765		pF	
Output Capacitance	C _{oss}			330			
Reverse Transfer Capacitance	C _{rss}			280			
Total Gate Charge ^c	Qg			67		nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -20 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -14 \text{ A}$		13.5			
Gate-Drain Charge ^c	Q _{gd}			14			
Gate Resistance	Rg	f = 1 MHz	0.5	2.5	5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			10	20		
Rise Time ^c	t _r	$V_{DD} = -20 \text{ V}, \text{ R}_{L} = 2 \Omega$		11	20	ns	
Turn-Off Delay Time ^c	t _{d(off)}			42	63		
Fall Time ^c	t _f			12	20		
Drain-Source Body Diode Ratings ar	d Characteri	istics T _C = 25 °C ^b					
Continuous Current	۱ _S				- 36	٨	
Pulsed Current	I _{SM}				- 100	A	
Forward Voltage ^a	V _{SD}	I _F = - 10 A, V _{GS} = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}			38	57	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 10 A, dl/dt = 100 A/μs		2.3	3.5	А	
Reverse Recovery Charge	Q _{rr}	1		40	60	nC	

Notes:

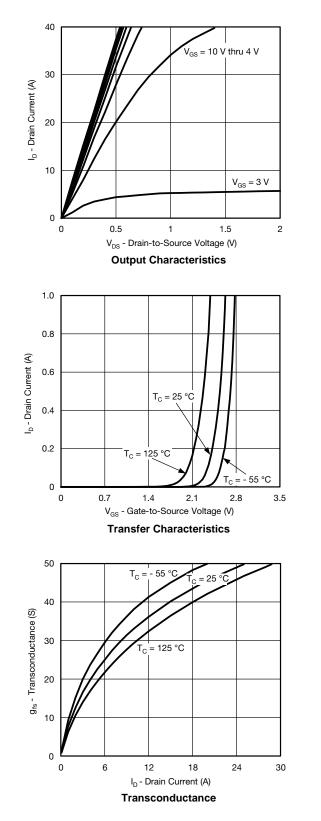
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

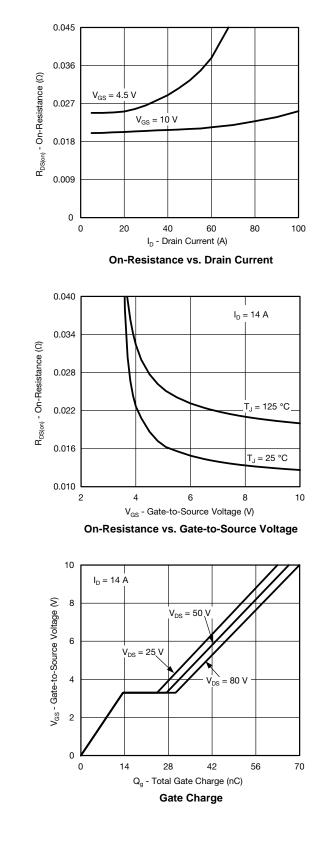
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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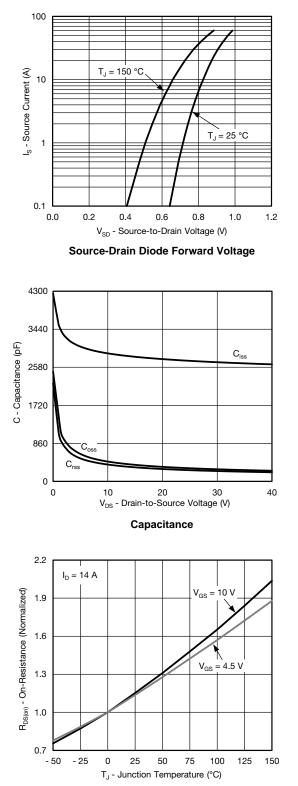


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

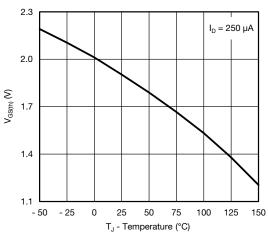




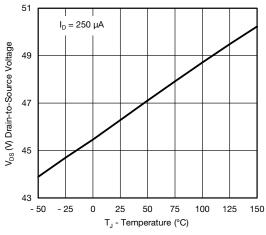
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



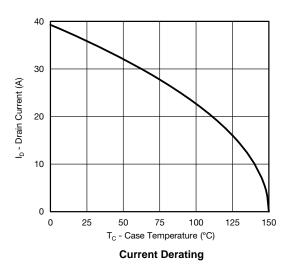
On-Resistance vs. Junction Temperature



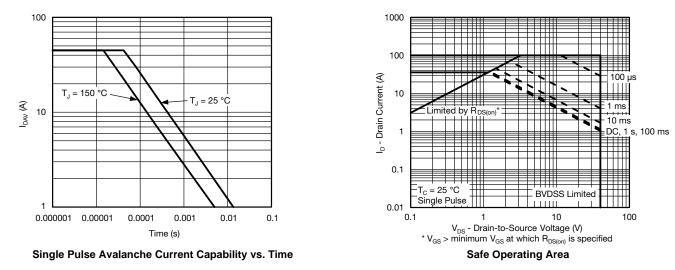
Threshold Voltage



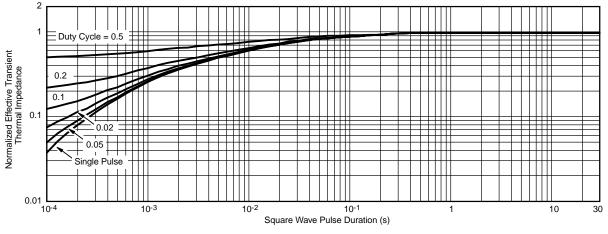
Drain Source Breakdown vs. Junction Temperature







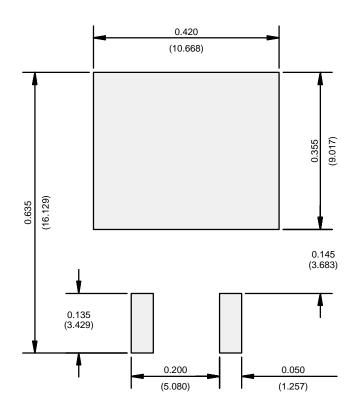
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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